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4-10-06

1. Name of conveying party(ies)
Byung-Jun SONG
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Seoul Laser Dieboard System Co., Ltd.
Internal Address:
Street Address: 13110 Sunstone Pointe
City: San Diego
State: California
Country: USA Zip: 92130
Additional name(s) & address(es) attached? Yes No

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3. Nature of conveyance/Execution Date(s):
Execution Date(s) March 1, 2006
 Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

4. Application or patent number(s): This document is being filed together with a new application.
A. Patent Application No (s)
B. Patent No (s)
6,128,940
Additional numbers attached? Yes No

04/10/06 BYUNG JUN SONG 6128940
40.00 BP

5. Name and address to whom correspondence concerning document should be mailed:
Name: Kyong Chan Lim
Internal Address:
Street Address: 13110 Sunstone Pointe
City: San Diego
State: California Zip: 92130
Phone Number: (858) 259-9467
Fax Number:
Email Address: kclimok@hotmail.com

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40
 Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information
a. Credit Card Last 4 Numbers _____
Expiration Date _____
b. Deposit Account Number _____
Authorized User Name _____

9. Signature: Kclim March 23, 2006
Signature Date
Kyong Chan Lim
Name of Person Signing
Total number of pages including cover sheet attachments and documents: 3

2. Name and address of additional receiving party

Name: Seoul Laser Dieboard System Co., Ltd.
Street Address: 1029-30 Hogae-dong, Dongan-ku
City: Anyang City
State: Kyunggido
Country: KOREA

ASSIGNMENT

U.S. Patent No.: 6,128,940
Title: FOLDING SYSTEM FOR A CUTTING BLADE
Issued: October 10, 2000

WHEREAS, I, Byung-Jun Song (hereinafter referred to as "ASSIGNOR"), owner of the entire right, title, and interest in U.S. Letters Patent No. 6,128,940, residing at 1029-30 Hokyedong, Anyang-si, Dongan-ky, Kyungki-do, Korea, is desirous of transferring all interest in, to and under said U.S. Letters Patent to Seoul Laser Dieboard System Co., Ltd. (hereinafter referred to as "ASSIGNEE 1"), a corporation operating in California, located at 13110 Sunstone Pointe, San Diego California 92130, and to Seoul Laser Dieboard System Co., Ltd. (hereinafter referred to as "ASSIGNEE 2"), a Korean Company, located at 1029-30 Hogaedong, Dongan-ku, Anyang City, Kyunggido, Korea. ASSIGNEE 1 and ASSIGNEE 2 (collectively referred to as "ASSIGNEES") are desirous of acquiring all interest in, to and under said U.S. Letters Patent.

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, Byung-Jun Song, the ASSIGNOR, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said U.S. Letters Patent, including any divisions and continuations deriving from said U.S. Letters Patent, and in and to any and all patents deriving from said U.S. Letters Patent in countries foreign to the United States.

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment is executed on the dates indicated below.

Byung-Jun SONG

Name of the ASSIGNOR



Signature of the ASSIGNOR

Mar 1. '06

Date of Assignment